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IFIP is the global non-profit federation of societies of ICT professionals that aims at achieving a worldwide professional and socially responsible development and application of information and communication technologies.

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The flagship event is the IFIP World Computer Congress, at which both invited and contributed papers are presented. Contributed papers are rigorously refereed and the rejection rate is high.

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Youngsoo Shin · Chi Ying Tsui
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Ricardo Reis (Eds.)

VLSI-SoC: Design for Reliability, Security, and Low Power

23rd IFIP WG 10.5/IEEE International Conference
on Very Large Scale Integration, VLSI-SoC 2015
Daejeon, Korea, October 5–7, 2015
Revised Selected Papers

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Preface

This book contains extended and revised versions of the highest quality papers, which were presented during the 23rd IFIP/IEEE WG10.5 International Conference on Very Large Scale Integration (VLSI-SoC), a global System-on-Chip Design & CAD conference. The 23rd conference was held at the Daejeon Convention Center, South Korea, during October 5–7, 2015. Previous conferences have taken place in Edinburgh, Scotland (1981); Trondheim, Norway (1983); Tokyo, Japan (1985); Vancouver, Canada (1987); Munich, Germany (1989); Edinburgh, Scotland (1991); Grenoble, France (1993); Chiba, Japan (1995); Gramado, Brazil (1997); Lisbon, Portugal (1997); Montpellier, France (2001); Darmstadt, Germany (2003); Perth, Australia (2005); Nice, France (2006); Atlanta, USA (2007); Rhodes Island, Greece (2008); Florianopolis, Brazil (2009); Madrid, Spain (2010); Kowloon, Hong Kong (2011), Santa Cruz, USA (2012), Istanbul, Turkey (2013), and Playa del Carmen, Mexico (2014).

The purpose of this conference, which was sponsored by IFIP TC 10 Working Group 10.5, the IEEE Council on Electronic Design Automation (CEDA), and by IEEE Circuits and Systems Society, with the In-Cooperation of ACM SIGDA, was to provide a forum for the exchange of ideas and presentation of industrial and academic research results in the field of microelectronics design. The current trend toward increasing chip integration and technology process advancements has brought new challenges both at the physical and system design levels, as well as in the test of these systems. VLSI-SoC conferences aim to address these exciting new issues.

The quality of submissions (117 regular papers from 28 countries, excluding PhD Forum and special sessions) made the selection process a very difficult one. Finally, 44 submissions were accepted as full papers and 17 as posters. Out of the 44 full papers presented at the conference, 10 papers were chosen by a selection committee to have an extended and revised version included in this book. The selection process of these papers considered the evaluation scores during the review process as well as the review forms provided by members of the Technical Program Committee and Session Chairs as a result of the presentations.

The chapters of this book have authors from China, Denmark, France, Germany, Hong Kong, Italy, Ireland, South Korea, The Netherlands, Switzerland, and the USA. The Technical Program Committee comprised 92 members from 24 countries.

VLSI-SoC 2015 was the culmination of the work of many dedicated volunteers: paper authors, reviewers, session chairs, invited speakers, and various committee chairs. We thank them all for their contribution.

This book is intended for the VLSI community, mainly those persons who did not have the chance to attend the conference. We hope you will enjoy reading this book and that you will find it useful in your professional life and for the development of the VLSI community as a whole.

August 2016

Youngsoo Shin
Chi Ying Tsui
Jae-Joon Kim
Kiyong Choi
Ricardo Reis

Organization

The IFIP/IEEE International Conference on Very Large Scale Integration-System-on-Chip (VLSI-SoC) 2015 took place during October 5–7, 2015 in the Daejeon Convention Center, South Korea. VLSI-SoC 2015 was the 23rd in a series of international conferences, sponsored by IFIP TC 10 Working Group 10.5 (VLSI), IEEE CEDA, and ACM SIGDA. The organization of the conference was done by the following people:

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Contents

On the Use of System-on-Chip Technology in Next-Generation Instruments Avionics for Space Exploration.	1
<i>Xabier Iturbe, Didier Keymeulen, Patrick Yiu, Daniel Berisford, Robert Carlson, Kevin Hand, and Emre Ozer</i>	
Fault Collapsing in Digital Circuits Using Fast Fault Dominance and Equivalence Analysis with SSBDs	23
<i>Raimund Ubar, Lembit Jürimägi, Elmet Orasson, and Jaan Raik</i>	
A Hardware Accelerator for Real Time Sliding Window Based Pedestrian Detection on High Resolution Images	46
<i>Asim Khan, Muhammad Umar Karim Khan, Muhammad Bilal, and Chong-Min Kyung</i>	
Wearable ECG SoC for Wireless Body Area Networks: Implementation with Fuzzy Decision Making Chip	67
<i>Manikandan Pandiyan and Geetha Mani</i>	
Delay Testing Based on Multiple Faulty Behaviors	87
<i>Masahiro Fujita</i>	
A Temperature-Aware Battery Cycle Life Model for Different Battery Chemistries	109
<i>Alberto Bocca, Alessandro Sassone, Donghwa Shin, Alberto Macii, Enrico Macii, and Massimo Poncino</i>	
A SAR Pipeline ADC Embedding Time Interleaved DAC Sharing for Ultra-low Power Camera Front Ends	131
<i>Anvesha Amaravati, Manan Chugh, and Arijit Raychowdhury</i>	
Electromagnetic Transmission of Intellectual Property Data to Protect FPGA Designs	150
<i>Lilian Bossuet, Pierre Bayon, and Viktor Fischer</i>	
JAIP-MP: A Four-Core Java Application Processor for Embedded Systems	170
<i>Chun-Jen Tsai, Tsung-Han Wu, Hung-Cheng Su, and Cheng-Yang Chen</i>	
Automatic Generation and Qualification of Assertions on Control Signals: A Time Window-Based Approach.	193
<i>Alessandro Danese, Francesca Filini, Tara Ghasempouri, and Graziano Pravadelli</i>	
Author Index	223